

Features

High isolation

◆ MFP: 3750V

4/6/8 PIN: 5000V

OFF-state output terminal voltage: 80 V (min)

Operating temperature range - 40 °C to 100 °C

Creepage distance

• MFP ≥ 5mm

• 4/6/8 PIN ≥ 7.4mm

Distance through insulation > 0.4mm

RoHS compliance

REACH compliance

Halogen free

Regulatory Approvals

• UL - UL1577

VDE - EN60747-5-5(VDE0884-5)

CQC – GB4943.1, GB8898

• IEC60065, IEC60950

Description

The CTR215 consists of two MOSFET and one photovoltaic chip optically coupled to a gallium arsenide Infrared-emitting diode in different package and lead forming options.

Applications

- Battery Management System (BMS)
- Security Systems
- Smart Meters
- Mechanical relay replacements
- General telecom switching
- Industrial controls
- Automatic measurement equipment

Package Type Naming Code

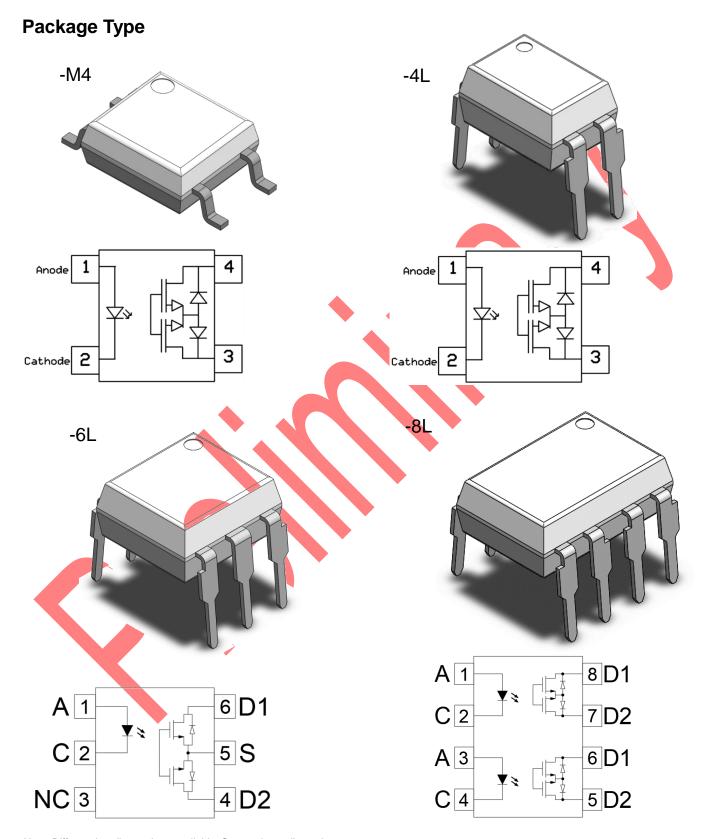
MFP : CTR215-M4

• 4PIN : CTR215-4L

• 6PIN : CTR215-6L

8PIN : CTR215-8L





Note: Different bending options available. See package dimension.



Absolute Maximum Rating at 25°C

Symbol	Paran	Ratings	Units	Notes	
\/	la elation valtage	M4	3750	Vrms	1
V _{iso}	Isolation voltage	4/6/8L	5000	Vrms	1
T _{OPR}	Operating temperature		-40 ~+110	°C	
T _{STG}	Storage temperature		-55 ~+125	°C	
T _{SOL}	Soldering temperature		260	°C	
Emitter					
I _F	LED forward current		20	mA	
I _{FP}	LED forward current (pulsed) (≤	100	mA		
V_R	LED reverse voltage	5	V		
P _{in}	Power dissipation	32	mW		
T _j	Junction Temperature		115	°C	
Detector			•		
V _{OFF}	OFF-state output terminal Voltage		80	V	
I _{ON}	ON-state Current	CTR215	700	mA	2
Po	Output Power dissipation	CTR215	500	mW	2
Tj	Junction Temperature		125	°C	

Note:

1: AC , 60s

2: Pule Duty : 20%



Electrical Characteristics

Typical values are measured at $T_A = 25^{\circ}$ C

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F = 10mA	-	1.4	1.6	V	
I _R	Reverse Current	V _R = 6V	-		5	μA	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min		Тур	Max	Units	Notes
I _{OFF}	OFF-state Current	V _{OFF} =80V	-	4	0.2	1	uA	
C _{OFF}	Output Capacitance	V _O = 0V, f=1 MHz	-		22	_	pF	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{FT}	Trigger LED Current	Ion=100mA	-	-	3	mA	
Ron	ON-state resistance	I _{ON} =100mA, I _F =5 mA, t < 1s	-	0.6	1	Ω	

Switching Characteristics

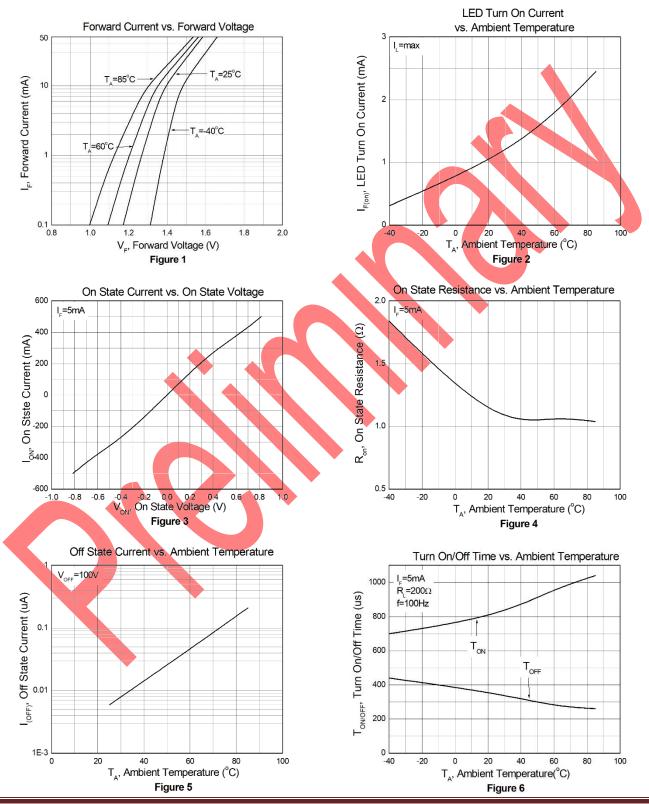
Symbol	Param	eters	Test Conditions	Min	Тур	Max	Units	Notes
Ton	Turn-on Ti <mark>me</mark>		See Fig. 7,	-	0.4	1	ms	
Toff	Turn-off Time		R _L =200Ω, V _{DD} =20V, I _F =10mA f=100Hz	-	0.4	1	ms	

Note:

3. Pulse duty: 20 %



Typical Characteristic Curves





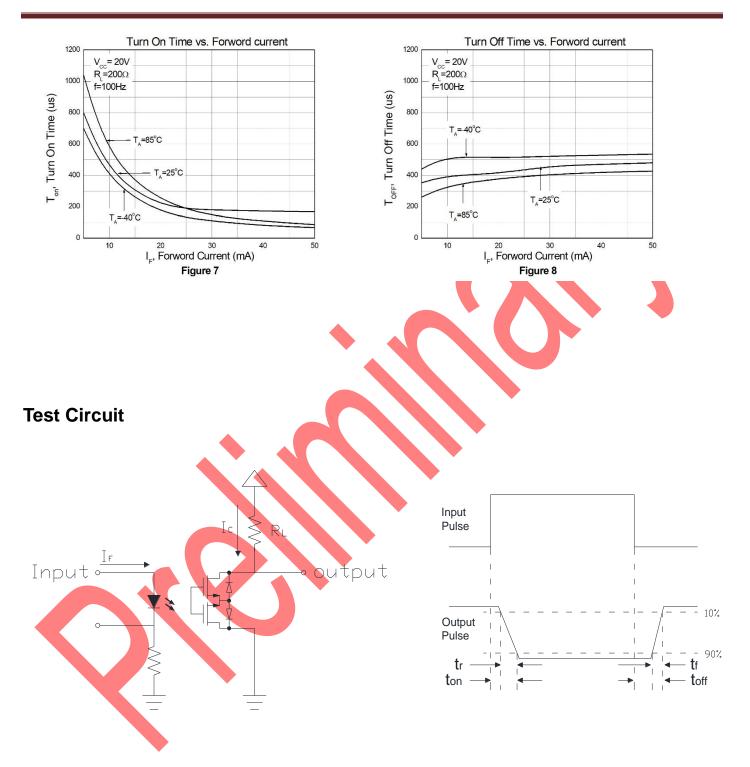
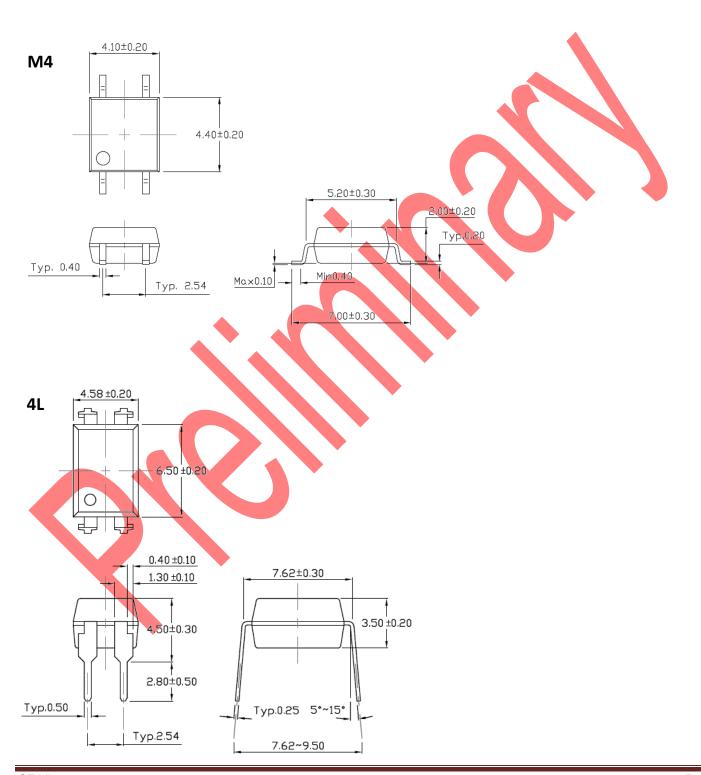


Figure 9: Switching Time Test Circuits

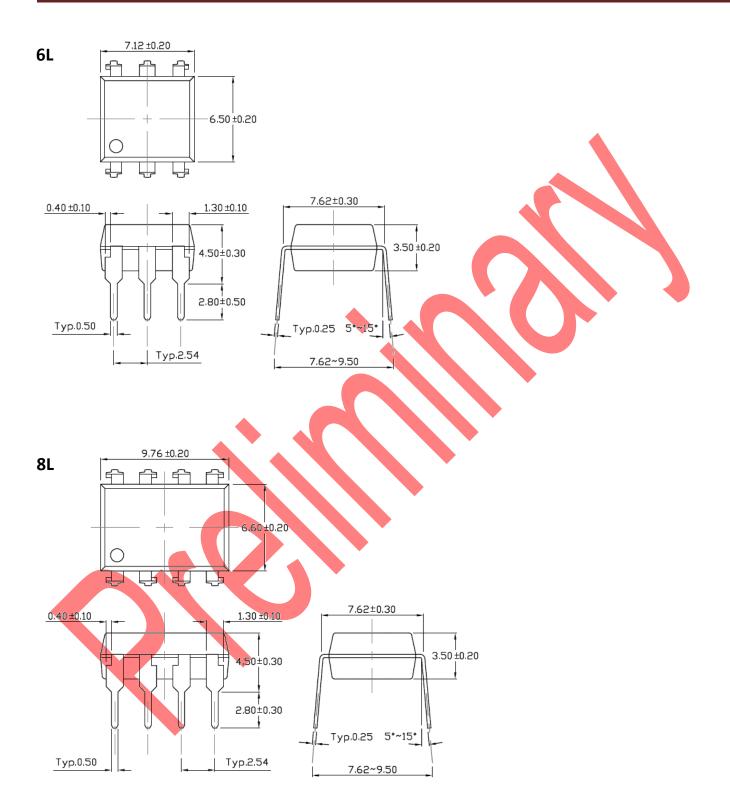


Package Dimension Dimensions in mm unless otherwise stated

Standard

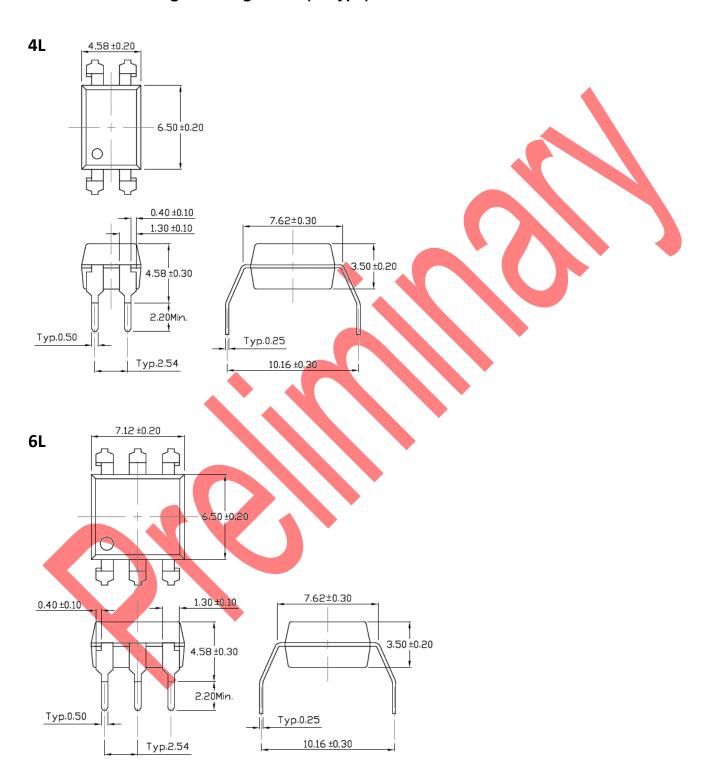




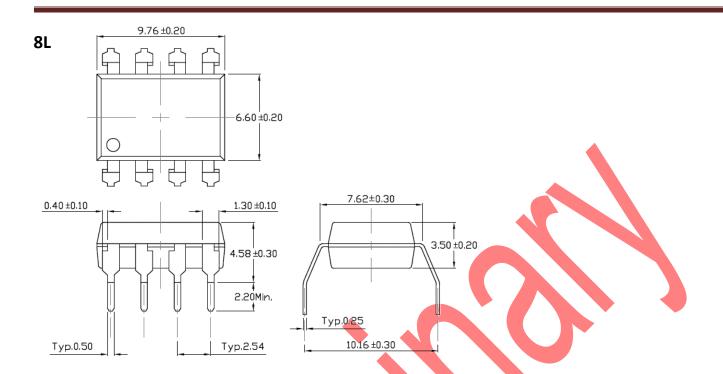




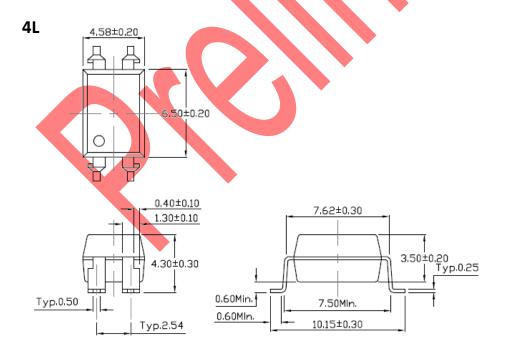
Wide Lead Forming – Through Hole (M Type)



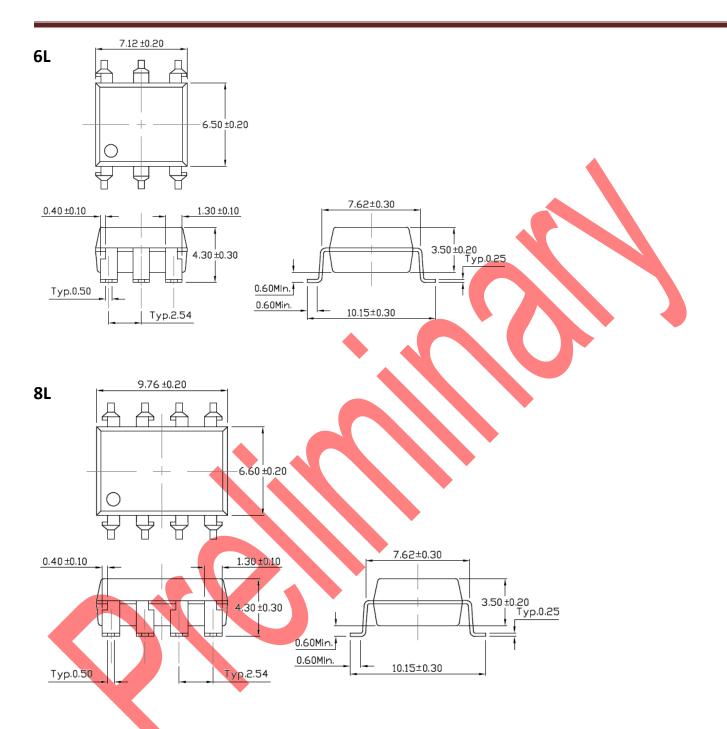




Surface Mount Forming (\$ Type)

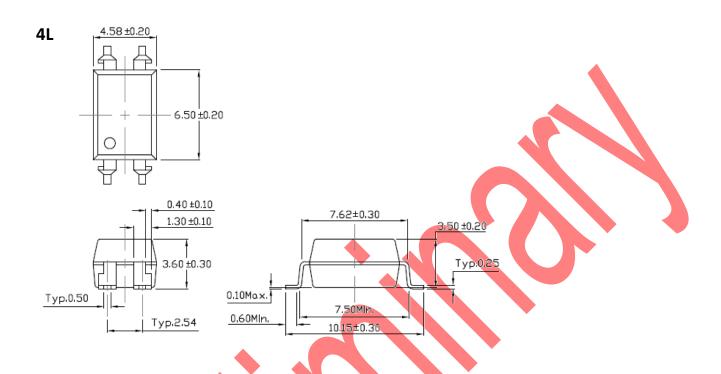


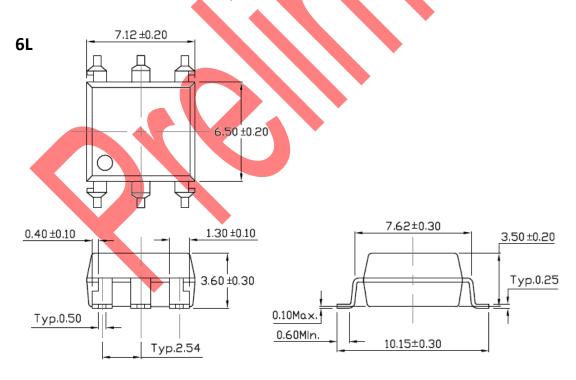




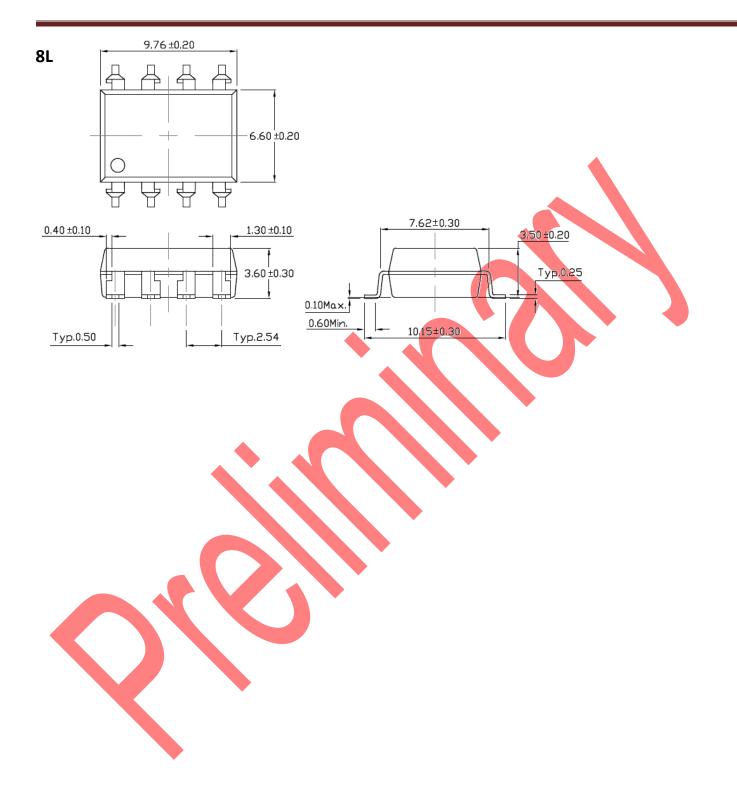


Surface Mount (Low Profile) Lead Forming (SL Type)





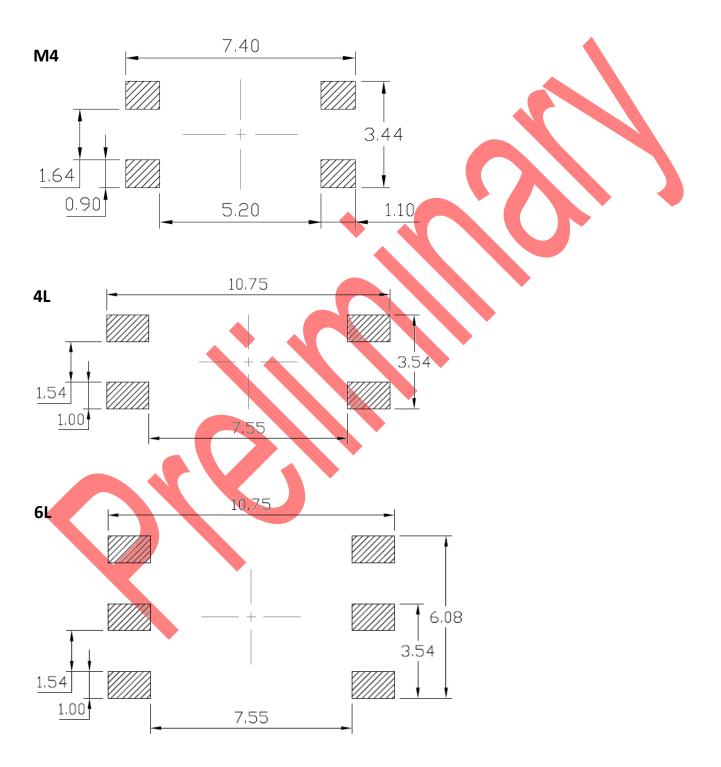




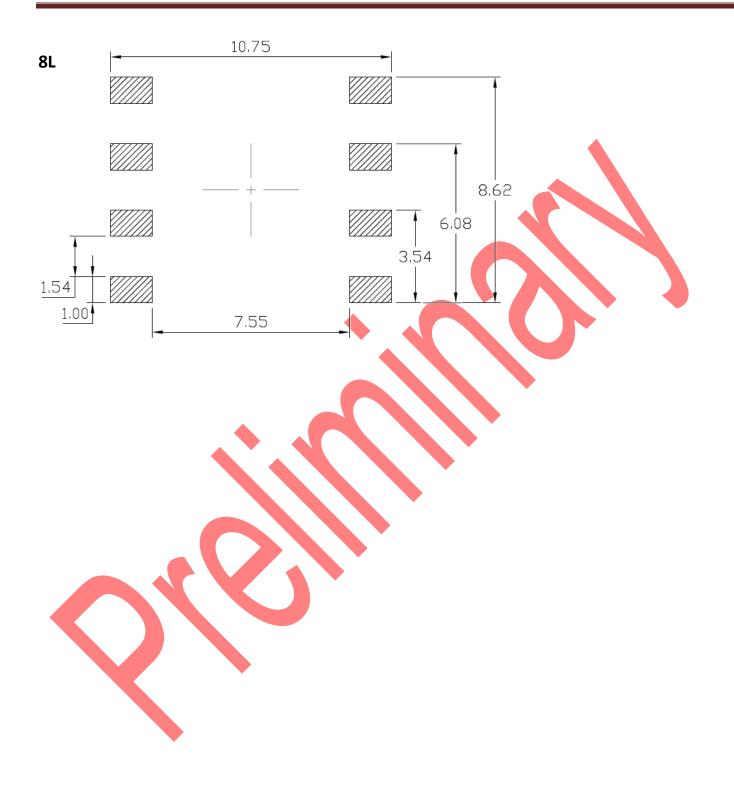


Recommended Solder Mask Dimensions in mm unless otherwise stated

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming

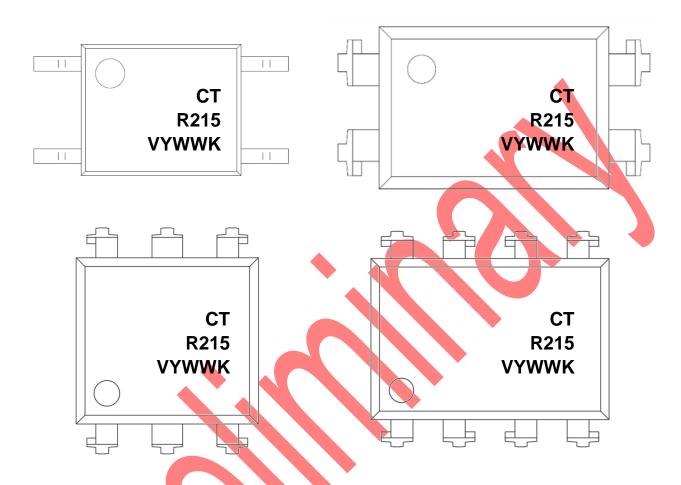








Marking Information



Note:

CT : Denotes "CT Micro"

R215 : Part Number

V : VDE Certification Mark Option

Y : Fiscal Year WW : Work Week

K : Manufacturing Code



Ordering Information

CTR215(V)(Y)(Z) - M4

CT = Denotes "CT Micro"

R215 = Product Number

V = VDE Certification Mark Option

Y = Lead form option (M, S, SL or none)

M4 = Package Type (M4 = M4, 4L, 6L, 8L)

Z = Tape and Reel Option (T1 or T2)

Option	M4 Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Tapping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Tapping	3000 Units/Reel

Option	4L Description	Quantity
None	Standard 4 Pin DIP	100 Units/Tube
M	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming- With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel

Option	6L Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel



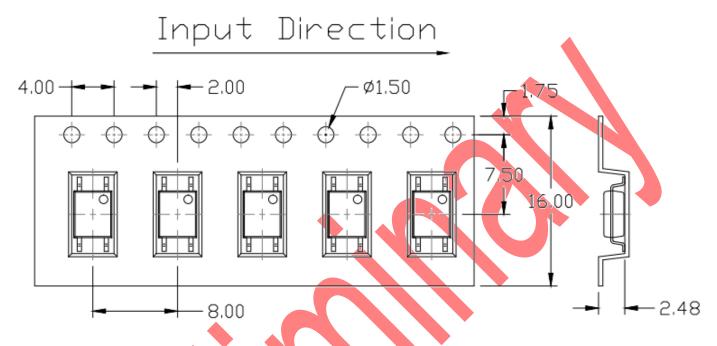
Option	Option 8L Description	
None	None Standard 8 Pin Dip	
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel

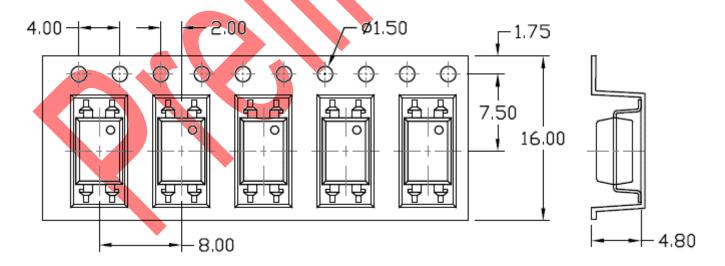




Carrier Tape Specifications Dimensions in mm unless otherwise stated

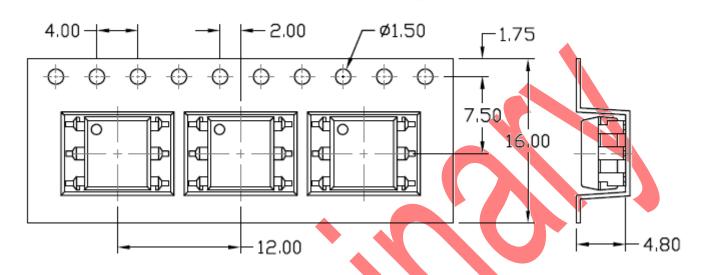
Option (S)(SL) T1

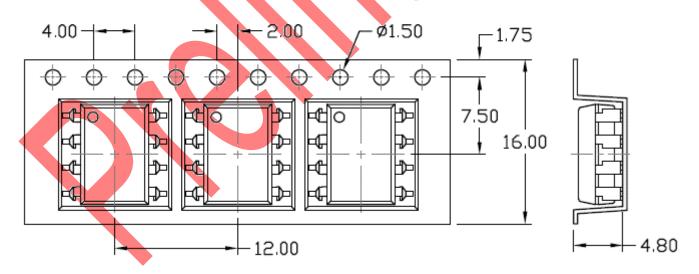






Input Direction

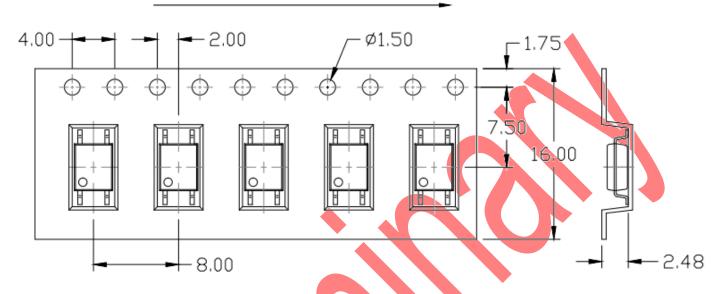


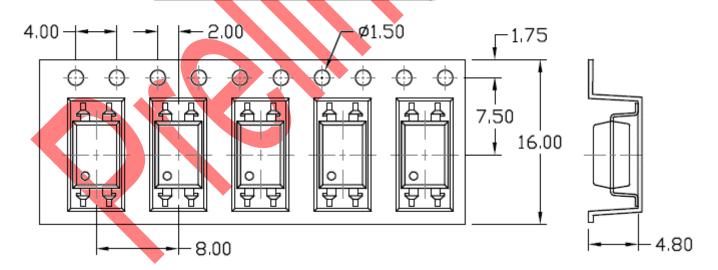




Option (S)(SL) T2

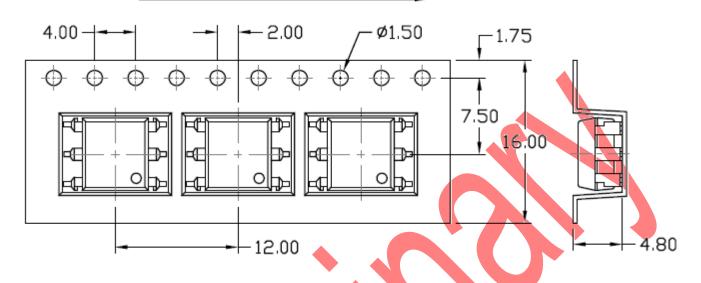
Input Direction

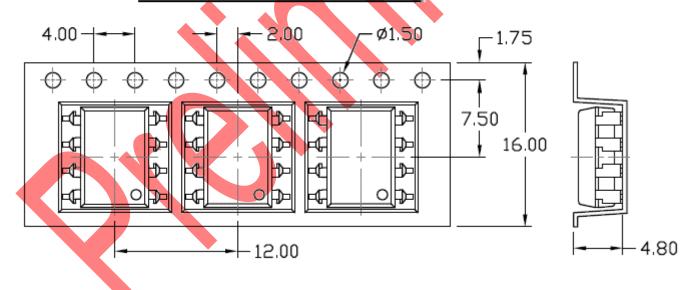




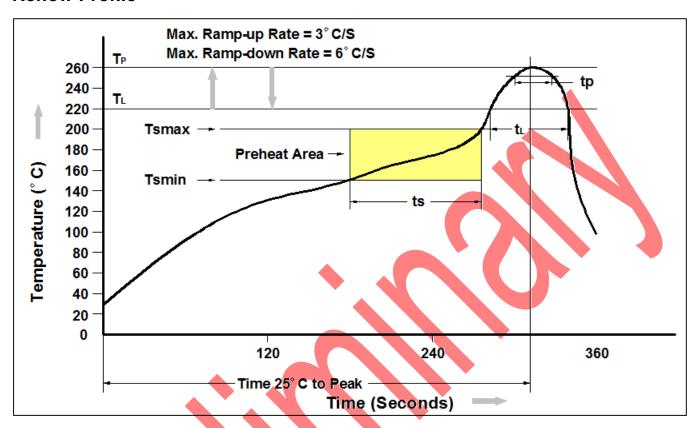


Input Direction





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t∟) Maintained Above (T∟)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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